

Thermally Conductive Products

Thermipad® TP 22338

Electrically insulating - double-sided self-adhesive

Structure: Thermipad® TP 22338 is a thermally conductive ceramic filled soft silicone film with very high thermal conductivity, electrical breakdown strength and high elasticity.

Characteristics: Due to the high compressibility of Thermipad® TP 22338 heat sources and heat sinks that have great unevenness, can be thermally bonded together. The housing itself can thus act as a heat sink, thereby saving space in the overall application. Thanks to the excellent conformability of Thermipad® TP 22338 the side faces of the components are reached, thereby increasing the contact area and thermal connection is further improved. The applied pressure is low, which preserves components, circuit boards and housings from damage. The very high elasticity also contributes to the mechanical damping within the application. The laminate provides defined film sides and increases the mechanical stability. Thermipad® TP 22338 is a soft and flexible material that can be processed quickly, easily and reliable.

Application: Thermipad® TP 22338 is particularly suitable for use in applications whereby heat is dissipated through different component heights or different tolerances and unevenness over a greater distance to a housing or where a heat sink needs to be. A selection of applications, e.g. SMD power modules, motor control and cooling systems, interfaces between vias in PCBs and housings or heat sinks, electrolytic capacitor, thermal sensors, high power diodes, heat pipes, CD-Rom cooling, CPU modules, battery chargers, UPS and SMPS.

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Colour: Thermipad® TP 22338 is supplied in grey.

Supply Format: Thermipad® TP 22338 is supplied in sheets and shapes according to customer specification and in mats (300mm x 400mm). Intermediate sizes of thicknesses are also available on request.

Storage Conditions: Thermipad® TP 22338 should be stored in its original packaging at max. 40°C.

Properties	Unit	Value
Filler	-	Thermally Conductive Ceramics
Material Thickness	mm	2.5
Tensile Strength	MPa	0.35
Hardness	Shore C	25
Dielectric Strength		
Voltage Ramp	V(AV)	>15000
Voltage Steps	V(AC)	>15000
Specific Volume Resistance	Ohm*m	1.0 x10 ¹⁰
Flammability		UL 94 VO
Thermal Conductivity	W/m*K	5.6
Thermal Transfer Resistance	°C/W	1.00
Operating Temperature	°C	-60 to180

Trademark Information: Thermipad® is a registered trademark of the company Dr. Dietrich Müller GmbH, Germany.

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Please note:

The information in this data sheet is based on our current knowledge and experience. They do not disengage the fabricator and user from own tests and inspections because of the plenty of possible effects. There is no judicial binding assurance of certain properties or of the qualification for a concrete application in our declaration. We recommend consulting us in individual cases. The acceptor of our products has to observe possible industrial property rights as well as present laws by himself.

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